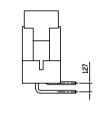
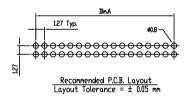


1





NOTE:

1. MATERIAL, HOUSING: HIGH TEMP PLASTIC, UL94-VO.BLACK

TERMINAL: COPPER ALLOY, SQ=0.40±0.03MM

TERMINAL: GOLD AT CONTACT.

G/F OVER 1um(40u")MIN Ni OVER ALL

3. SPEC.:

PRODUCT SPEC: GS-12-629 PACKING SPEC: GS-14-1420

4. THE HSG. WILL WITHSTAND EXPOSURE TO 260C PEAK TEMP. FOR 5 SEC. IN A WAVE SOLDER APPLICATION

WITH A PCB.

5. PRODUCT NUMBERING:



TADI	г	1

DASH No. Dim.	Amount of Pins	Dim.A	Dim.B	Dim.C
-000 06 XX LF	6	2.54	18.31	8.46
-000 10 XX LF	10	5.08	20.85	11.00
-000 12 XX LF	12	6.35	22.12	12.27
-000 14 XX LF	14	7.62	23.39	13.54
-000 16 XX LF	16	8.89	24.66	14.81
-000 20 XX LF	20	11.43	27.20	17.35
-000 26 XX LF	26	15.24	31.01	21.16
-000 30 XX LF	30	17.78	33.55	23.70
-000 34 XX LF	34	20.32	36.09	26.24
-000 40 XX LF	40	24.13	39.90	30.05
-000 44 XX LF	44	26.67	42.44	32.59
-000 50 XX LF	50	30.48	46.25	36.40
-000 60 XX LF	60	36.83	52.60	42.75
-000 64 XX LF	64	39.37	55.14	45.29
-000 66 XX LF	66	40.64	56.41	46.56
-000 68 XX LF	68	41.91	57.68	47.83

surface /tolerance|projectionproduct family mat'l. code IS□1302 V ISD1101 ISD406 MINITEK specifie dtitle ltrecn nødr date toleraņces unless other 0.X±0.38 A |T09-1117|S.LIN|09/15/09| 1.27X1.27MM BTB EHECT HEADER B T10-0026 S.LIN 01/20/10 0.XX±0.25 RIGHT ANGLE TH scale 2:1 C EIX-N-010366 ZK 01/16/12 0°±2° 0.XXX±0.10 dwg no sheetlof1 size STERLING LIN 09/15/09 engrsterling Lin 09/15/09 20021612 GRAY HSIEH 09/15/09 appd Joseph type Product Customer Drawing 09/15/09 sheet revisionc index sheet 1

PDS: Rev :C3

В

form: A4mmXLc

STATUS:Released

Printed: Mar 0242012